

IN THE CLAIMS

Please amend the claims as follows:

Claims 1-23 (Canceled).

Claim 24 (New): A high-impedance substrate comprising:

a first layer or sheet made of insulating material, having a first face and a second face in a form of a lower face and an upper face; and conductor patterns mechanically linked to the substrate, wherein at least some of the conductor patterns mechanically linked to the substrate are associated with a magnetic tile placed on or above one of the first and second faces of the substrate, and at least one electrical interconnection puts two points in electrical contact distinct from one another of one of the conductor patterns mechanically linked to the substrate, this conductor pattern having an assigned magnetic tile, passing above the magnetic tile associated with the conductor pattern mechanically linked to the substrate.

Claim 25 (New): The high-impedance substrate as claimed in claim 24, wherein the conductor patterns are constituted by conductive tracks deposited on at least one of the upper or lower faces of the substrate.

Claim 26 (New): The high-impedance substrate as claimed in claim 24, wherein the conductor patterns are constituted by conductive tracks deposited on at least one of the upper or lower faces of the substrate and together forming an electrical circuit with electronic components.

Claim 27 (New): The high-impedance substrate as claimed in claim 26, wherein the electronic components are elements having a resistance value and a capacity value.

Claim 28 (New): The high-impedance substrate as claimed in claim 27, wherein the electronic components comprise one or more active elements having a capacity value that can vary as a function of a value of an electrical variable applied to the one or more active elements.

Claim 29 (New): The high-impedance substrate as claimed in claim 24, further comprising a second layer or sheet having an upper face opposite the lower face of the first layer or sheet, and a lower face, and wherein a part at least of each of the conductor patterns is mechanically linked to at least one of the upper and lower faces of the second sheet or layer.

Claim 30 (New): The high-impedance substrate as claimed in claim 24, further comprising a second layer or sheet having an upper face opposite the lower face of the first layer or sheet, and a lower face, and wherein all of the conductor patterns are mechanically linked to at least one of the upper and lower faces of the second sheet or layer.

Claim 31 (New): The high-impedance substrate as claimed in claim 26, further comprising a second layer or sheet having an upper face opposite the lower face of the first layer or sheet, and a lower face, and all of the conductor patterns and all of the electronic components forming an electrical circuit with the conductor patterns are mechanically linked to at least one of the upper and lower faces of the second sheet or layer.

Claim 32 (New): The high-impedance substrate as claimed in claim 24, further comprising a ground plane situated underneath the first layer or sheet opposite the lower face of the first layer or sheet.

Claim 33 (New): The high-impedance substrate as claimed in claim 29, further comprising a ground plane situated underneath the second layer or sheet opposite the lower face of the second layer or sheet.

Claim 34 (New): The high-impedance substrate as claimed in claim 29, further comprising a ground plane situated between the first and second layers or sheets opposite the lower face of the first layer or sheet.

Claim 35 (New): The high-impedance substrate as claimed in claim 32, wherein the ground plane is constituted by plating of the lower face of the first layer or sheet.

Claim 36 (New): The high-impedance substrate as claimed in claim 33, wherein the ground plane is constituted by plating of the lower face of the second layer or sheet.

Claim 37 (New): The high-impedance substrate as claimed in claim 24, further comprising a ground plane situated above the first layer or sheet opposite the upper face of the first layer or sheet.

Claim 38 (New): The high-impedance substrate as claimed in claim 37, wherein the ground plane is constituted by a metallization of the upper face of the first layer or sheet.

Claim 39 (New): The high-impedance substrate as claimed in claim 24, wherein the magnetic tiles are mechanically linked to the upper face of the first layer or sheet.

Claim 40 (New): The high-impedance substrate as claimed in claim 24, comprising a plurality of electrical interconnections each putting two distinct points in electrical contact with one or the other of the conductor pattern mechanically linked to the substrate passing above the magnetic tile associated with the conductor pattern, the conductor pattern and the interconnections together forming a solenoid around the magnetic tile.

Claim 41 (New): The high-impedance substrate as claimed in claim 29, wherein the conductor patterns with which a magnetic tile is associated each comprise a plurality of electrical interconnections each putting two distinct points in contact electrical with one another of the conductor pattern mechanically linked to the substrate passing above the magnetic tile associated with the conductor pattern, a first part of the conductor pattern and the interconnections together forming a solenoid around the magnetic tile, a second part of the pattern forming with capacitive and or resistive elements a circuit connecting the capacitive and/or resistive elements in parallel or in series on the solenoid.

Claim 42 (New): The high-impedance substrate as claimed in claim 24, wherein the magnetic tiles comprise rubber or plastic material loaded with a magnetic material powder.

Claim 43 (New): The high-impedance substrate as claimed in claim 42, wherein volume fraction of magnetic material powder of the rubber or of the plastic material forming the magnetic tiles is greater than 30%.

Claim 44 (New): The high-impedance substrate as claimed in claim 24, wherein the magnetic tiles comprise a material constituted by a stack of magnetic and insulating layers.

Claim 45 (New): The high-impedance substrate as claimed in claim 24, wherein a cover rate of a face carrying the magnetic tiles per the magnetic tiles is greater than 10%.

Claim 46 (New): The high-impedance substrate as claimed in claim 24, wherein a cover rate of a face carrying the magnetic tiles per the magnetic tiles is greater than 50%.